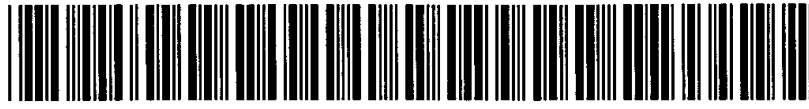


L Number	Hits	Search Text	DB	Time stamp
-	114	((laminating) with (thermoset\$2 or epoxy) with (resin)) and packaging	USPAT; US-PGPUB	2003/03/14 15:31
-	82	((laminating) with (thermoset\$2 or epoxy) with (resin)) and packaging) and (cure or curing or cured)	USPAT; US-PGPUB	2003/03/14 15:30
-	106	((laminating) with (thermoset\$4 or epoxy) with (resin)) and packaging and (cure or curing or cured)	USPAT; US-PGPUB	2003/03/14 15:55
-	1858	((sheet or layer or film or solid) with (thermoset\$4 or epoxy) with (resin)) and packaging and (cure or curing or cured)	USPAT; US-PGPUB	2003/03/14 15:57
-	907	((sheet or solid) with (thermoset\$4 or epoxy) with (resin)) and packaging and (cure or curing or cured)	USPAT; US-PGPUB	2003/03/14 16:03
-	185	((solid) with (epoxy) with (resin)) and packaging and (cure or curing or cured) and (IC or "integrated circuit" or semiconductor)	USPAT; US-PGPUB	2003/03/14 16:00
-	366	((sheet) with (thermoset\$4 or epoxy) with (resin)) and packaging and (cure or curing or cured)	USPAT; US-PGPUB	2003/03/14 16:05
-	1	("5,879,568").PN.	USPAT; US-PGPUB	2003/03/14 16:04
-	191	((sheet with (thermoset\$4 or epoxy) with (resin)) and(cure or curing or cured) and (heat or heating) and (packaging) and (IC or "integrated circuit" or semiconductor)	USPAT; US-PGPUB	2003/03/14 17:10
-	171	"hot melt" with (definition or define)	USPAT; US-PGPUB	2003/03/14 16:19
-	80	("hot melt" with (definition or define)) and resin	USPAT; US-PGPUB	2003/03/14 16:38
-	1	("6350664").PN.	USPAT; US-PGPUB	2003/03/14 17:21
-	7	("4043027"   "6130116"   "6184064"   "6190946"   "6197616"   "6204091"   "6221751").PN.	USPAT	2003/03/14 17:10
-	1	("6262513").PN.	USPAT; US-PGPUB	2003/03/14 17:50
-	4	("4364017"   "4734608"   "5010270"   "5243250").PN.	USPAT	2003/03/14 17:22
-	0	("4,602,31").PN.	USPAT; US-PGPUB	2003/03/14 17:50
-	1	("4,602,318").PN.	USPAT; US-PGPUB	2003/03/14 17:50
-	75	(curing near2 agent) with capsule	USPAT; US-PGPUB	2003/03/17 15:56
-	19	((curing near2 agent) with capsule ) with (epoxy)	USPAT; US-PGPUB	2003/03/17 16:03
-	66	epoxy with ("anti foam" or "anti foaming")	USPAT; US-PGPUB	2003/03/17 16:15
-	239	(expel or expelling) with air with (sheet or film)	USPAT; US-PGPUB	2003/03/17 16:20
-	25	((expel or expelling) with air with (sheet or film)) and (epoxy with resin)	USPAT; US-PGPUB	2003/03/17 16:19
-	35	((expel or expelling) with air with (sheet or film)) and (epoxy)	USPAT; US-PGPUB	2003/03/17 16:19
-	10	((expel or expelling) with air with (sheet or film)) and (epoxy)) not ((expel or expelling) with air with (sheet or film)) and (epoxy with resin))	USPAT; US-PGPUB	2003/03/17 16:19
-	733	(expel\$4) with air with (sheet or film or layer or encapsulant or encapsulation)	USPAT; US-PGPUB	2003/03/17 16:58
-	50	((expel\$4) with air with (sheet or film or layer or encapsulant or encapsulation)) and (IC or (packaging and (IC or semiconductor or chip)) or chip)	USPAT; US-PGPUB	2003/03/17 16:23
-	4	("5074036"   "5720100"   "5843251"   "6077382").PN.	USPAT	2003/03/17 16:24
-	0	6312551.URPN.	USPAT	2003/03/17 16:25
-	2	("5767575"   "5920126").PN.	USPAT	2003/03/17 16:26

-	2	6153939.URPN.	USPAT	2003/03/17 16:26
-	10	("2308453"   "2697253"   "5049055"   "5099090"   "5123823"   "5385869"   "5522713"   "5609889"   "5766535"   "5766972").PN.	USPAT	2003/03/17 16:27
-	0	5554413.URPN.	USPAT	2003/03/17 16:29
-	8	("3597816"   "5009744"   "5046236"   "5153859"   "5217550"   "5261986"   "5316602"   "5356512").PN.	USPAT	2003/03/17 16:30
-	6	("4452659"   "4539063"   "4859269"   "4902371"   "5047110"   "5073223").PN.	USPAT	2003/03/17 16:31
-	2	5217550.URPN.	USPAT	2003/03/17 16:32
-	3	("4799984"   "4929295"   "5009744").PN.	USPAT	2003/03/17 16:33
-	1561	((eliminat\$3 or reducing or reduce or preventing) with air with (sheet or film or layer)) and (IC or (packaging and (IC or semiconductor or chip)) or chip or semiconductor)	USPAT; US-PGPUB	2003/03/17 16:40
-	254	((eliminat\$3 or reducing or reduce or preventing) with air with (sheet or film or layer)) and (IC or (packaging and (IC or semiconductor or chip)) or chip or semiconductor)) and (epoxy with resin)	USPAT; US-PGPUB	2003/03/17 16:42
-	4	("5420452"   "6020590"   "6242746"   "6262408").PN.	USPAT	2003/03/17 16:51
-	0	6392217.URPN.	USPAT	2003/03/17 16:52
-	351	(expel\$4) with air ) and ((lamination or laminating or laminated) same (sheet or "epoxy resin"))	USPAT; US-PGPUB	2003/03/17 17:00
-	74	((expel\$4) with air ) and ((lamination or laminating or laminated) same (sheet or "epoxy resin")) and (IC or (packaging and (IC or semiconductor or chip)) or chip or semiconductor)	USPAT; US-PGPUB	2003/03/17 17:00



Creation date: 31-07-2003  
Indexing Officer: PHOENIX - PHOENIX  
Team: PhxAdministrator  
Dossier: 09660484

Legal Date: 17-03-2003

No.	Doccode	Number of pages
1	SRNT	2

Total number of pages: 2

Remarks:

Order of re-scan issued on .....